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(54) THROUGH-HOLE FILLING RESIN COMPOSITION AND MULTILAYER PRINTED WIRING BOARD

(57)Abstract:

PROBLEM TO BE SOLVED: To provide a multilayer printed wiring board, in which a through-hole and a via hole are ensured of connection reliability by a method, wherein the metal particles contained in resin composition which is filled into a through-hole are prevented from subsiding, and the filler is restrained from shrinking upon curing.

SOLUTION: Interlayer resin insulating layers and conductor layers are alternately laminated on a board, and inner and outer conductor layers are connected together through via holes to form a build-up wiring layer for the formation of a multilayer printed wiring board, wherein a through-hole is provided to the board for electrically connecting the front and rear of the board together, a non-conductive filler which contains granular material is filled into the through-hole, a conductor layer is formed on the exposed surface of the filler in the through-hole, and the filler is composed of a granular material, resin, and inorganic ultramicroscopic powder.

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